



MOS RAMs

MM2101, MM2101-1, MM2101-2

MM2101, MM2101-1, MM2101-2 1024-bit (256 × 4) static MOS RAM with separate I/O

general description

The National MM2101 is a 256 word by 4 bit static random access memory element fabricated using N-Channel enhancement mode Silicon Gate technology. Static storage cells eliminate the need for refresh and the additional peripheral circuitry associated with refresh. The data is read out nondestructively and has the same polarity as the input data.

The 2101 is directly TTL compatible in all respects: inputs, outputs, and a single +5 V supply. Two chip-enables allow easy selection of an individual package when outputs are OR-tied. An output disable is provided so that data inputs and outputs can be tied for common I/O systems. The features of this memory device can be combined to make a low cost, high performance, and easy to manufacture memory system.

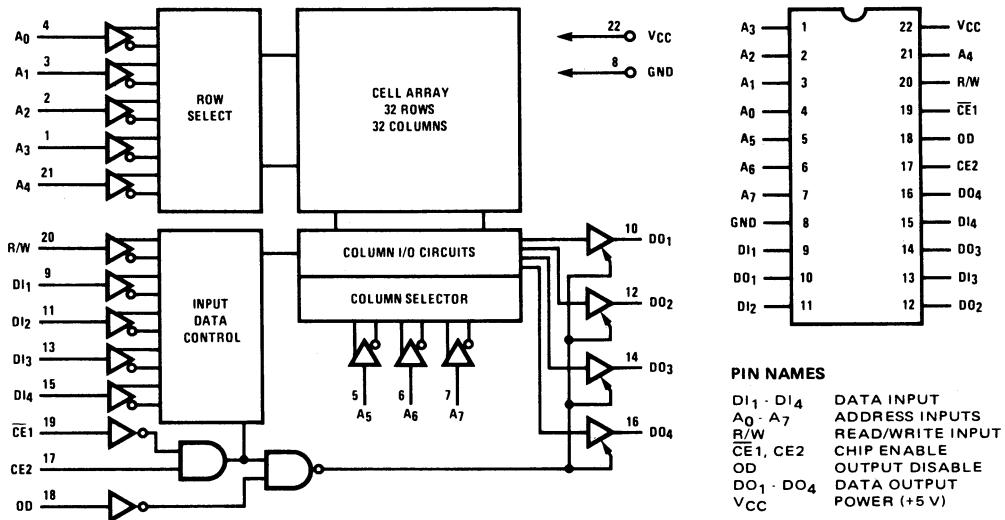
National's silicon gate technology also provides protection against contamination, and permits the use of low cost Epoxy B packaging.

features

- Organization 256 Words by 4 Bits
- Access Time – 0.5 to 1.0 μ s Max.
- Single +5 V Supply Voltage
- Directly TTL Compatible – All Inputs and Outputs
- Static MOS – No Clocks or Refreshing Required
- Simple Memory Expansion – Chip Enable Input
- Low Cost Packaging – 22 Pin Epoxy B Dual-In-Line Configuration
- Low Power – Typically 150 mW
- Tri-State[®] Output – OR-Tie Capability
- Output Disable Provided for Ease of Use in Common Data Bus Systems

1

block and connection diagrams



Order Number MM2101D,
MM2101-1D or MM2101-2D
See Package 5

Order Number MM2101-N,
MM2101-1N or MM2101-2N
See Package 17

absolute maximum ratings

Ambient Temperature Under Bias 0°C to +70°C
 Storage Temperature -65°C to +150°C
 Voltage on Any Pin With Respect to Ground -0.5 V to +7 V
 Power Dissipation 1 Watt

dc electrical characteristics $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$ unless otherwise specified.

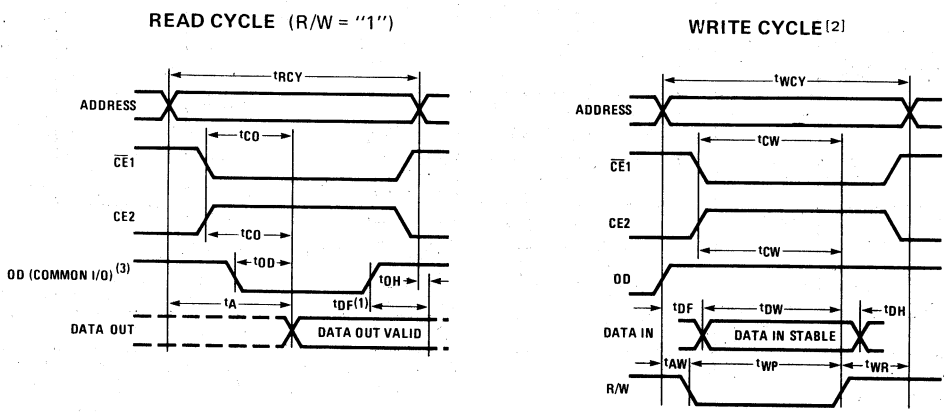
Symbol	Parameter	Min.	Typ. (1)	Max.	Unit	Test Conditions
I _{LI}	Input Current			10	μA	$V_{IN} = 0$ to 5.25 V
I _{LOH}	I/O Leakage Current (2)			15	μA	$\overline{CE1} = 2.2\text{ V}$, $V_{OUT} = 4.0\text{ V}$
I _{LOL}	I/O Leakage Current (2)			-50	μA	$\overline{CE1} = 2.2\text{ V}$, $V_{OUT} = 0.45\text{ V}$
I _{CC1}	Power Supply Current		30	60	mA	$V_{IN} = 5.25\text{ V}$, $I_O = 0\text{ mA}$ $T_A = 25^\circ\text{C}$
I _{CC2}	Power Supply Current			70	mA	$V_{IN} = 5.25\text{ V}$, $I_O = 0\text{ mA}$ $T_A = 0^\circ\text{C}$
V _{IL}	Input "Low" Voltage	-0.5		+0.65	V	
V _{IH}	Input "High" Voltage	2.2		V_{CC}	V	
V _{OL}	Output "Low" Voltage			+0.45	V	I _{OL} = 2.0 mA
V _{OH}	Output "High" Voltage	2.2			V	I _{OH} = -150 μA

Note 1: Typical values are for $T_A = 25^\circ\text{C}$ and nominal supply voltage.
 Note 2: Input and Output tied together.

capacitance $T_A = 25^\circ\text{C}$, $f = 1\text{ MHz}$

Symbol	Test	Limits (pF)	
		Typ.	Max.
C _{IN}	Input Capacitance (All Input Pins) $V_{IN} = 0\text{ V}$	4	8
C _{OUT}	Output Capacitance $V_{OUT} = 0\text{ V}$	8	12

switching time waveforms



Note 1: t_{DF} is with respect to the trailing edge of $\overline{CE1}$, $\overline{CE2}$, or OD, whichever occurs first.
 Note 2: During the write cycle, OD is a logical 1 for common I/O and "don't care" for separate I/O operation.
 Note 3: OD should be tied low for separate I/O operation.

ac electrical characteristics $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$, unless otherwise specified.

MM2101

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
READ CYCLE						
tRCY	Read Cycle	1,000			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tA	Access Time			1,000	ns	
tCO	Chip Enable to Output			800	ns	
tOD	Output Disable to Output			700	ns	
tDF ^[1]	Data Output to High Z State	0		200	ns	
tOH	Previous Data Read Valid after change of Address	0			ns	

WRITE CYCLE

tWCY	Write Cycle	1,000			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tAW	Write Delay	150			ns	
tCW	Chip Enable to Write	900			ns	
tDW	Data Setup	700			ns	
tDH	Data Hold	100			ns	
tWP	Write Pulse	750			ns	
tWR	Write Recovery	50			ns	

MM2101-1 (500 ns Access Time)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
READ CYCLE						
tRCY	Read Cycle	500			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tA	Access Time			500	ns	
tCO	Chip Enable to Output			350	ns	
tOD	Output Disable to Output			300	ns	
tDF ^[1]	Data Output to High Z State	0		150	ns	
tOH	Previous Data Read Valid after change of Address	0			ns	

WRITE CYCLE

tWCY	Write Cycle	500			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tAW	Write Delay	100			ns	
tCW	Chip Enable to Write	400			ns	
tDW	Data Setup	280			ns	
tDH	Data Hold	100			ns	
tWP	Write Pulse	300			ns	
tWR	Write Recovery	50			ns	

MM2101-2 (650 ns Access Time)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
READ CYCLE						
tRCY	Read Cycle	650			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tA	Access Time			650	ns	
tCO	Chip Enable to Output			400	ns	
tOD	Output Disable to Output			350	ns	
tDF ^[1]	Data Output to High Z State	0		150	ns	
tOH	Previous Data Read Valid after change of Address	0			ns	

WRITE CYCLE

tWCY	Write Cycle	650			ns	Input Pulse Levels: +0.65 to +2.2 V Input Pulse Rise and Fall Times: 20 ns Timing Measurement Reference Level: 1.5 V Output Load: 1 TTL Gate and $C_L = 100\text{ pF}$
tAW	Write Delay	150			ns	
tCW	Chip Enable to Write	550			ns	
tDW	Data Setup	400			ns	
tDH	Data Hold	100			ns	
tWP	Write Pulse	400			ns	
tWR	Write Recovery	50			ns	

Note 1: tDF is with respect to the trailing edge of $\overline{CE1}$, $\overline{CE2}$, or OD, whichever occurs first.